

ADHESIVES AND ADHESIVE COMPOSITIONS CONTAINING THIOETHER GROUPS

Abstract of the Disclosure

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In one aspect, the invention provides a curable composition comprising a mixture of epoxy resin, catalyst and an epoxy reactive thioether-containing compound and the resulting adhesives. The resulting adhesives are water and/or solvent resistant and bond to plastics such as ABS, polycarbonate, and PMMA; polyimide; noble metals such as gold and

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palladium; and silicon-containing materials such as silicon wafer die and silicon dioxide.

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